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Anyang-si, Gyeonggi-do, Korea

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August 13, 2019

Federal Communications Commission  
Equipment Authorization Branch  
7435 Oakland Mills Road  
Columbia, MD 21046

**Class II Permissive Change Cover Letter**  
**SUBJECT: Class II Permissive Change for FCC ID : VSOXR-150**

To Whom It May Concern:

This is to request a Class II permissive change for FCC ID: VSOXR-150, originally granted on 09/15/2010. We changed the following points from the original model.

- Partial change of chips on the PCB board and single output due to software.  
(Using software, adjust the frequency to match Part90 and delete 25kHz from channel spacing 12.5kHz and 25kHz. In addition, we used 2W and 5W, but deleted 2W as a program and used only 5W.)
- Meanwhile we submit the following documents related to this change. There is no change before and after change except for these documents.

✓	Test Report & SAR Report
	External Photo
✓	Internal Photo
✓	User Manual
	Label drawing/ location
✓	Block Diagram
✓	Schematic
✓	BLK DIA
✓	Parts List

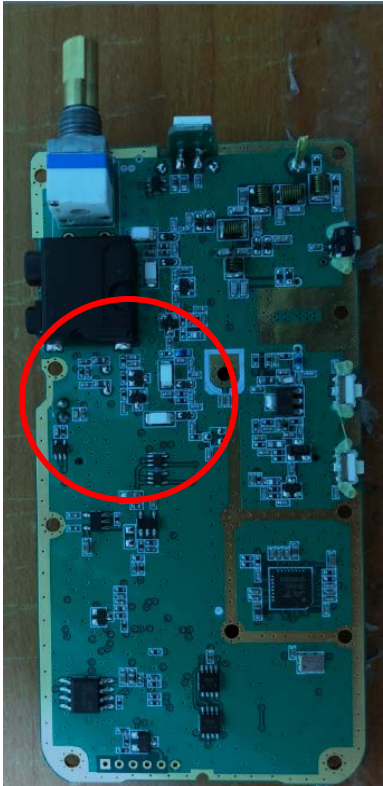

This time, we performed the testing and confirmed that this product still meets the minimum requirements of the applicable rules of FCC. Please refer to the test report submitted with this application.


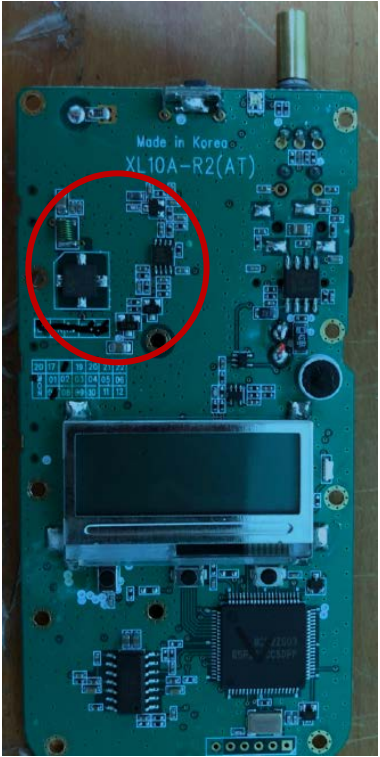
Sincerely,

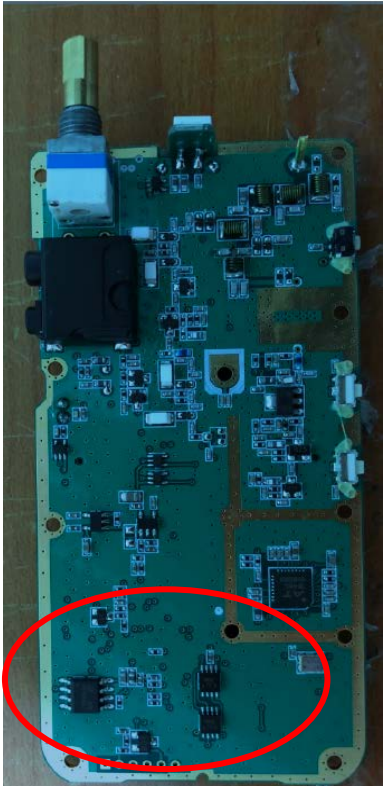



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*Hwan-Dae Kim / Chief Engineer*  
YEONHWA M TECH CO.,LTD

XR-150	Original	After the change
After the change	Changed to BPF using Barry Cap Diode due to 'RX' stage 'SAW' filter termination.	
comparison	 The image shows the original PCB with a red circle highlighting the SAW filter area. The filter is a small, rectangular component with a white label, located in the upper-middle section of the board.	 The image shows the modified PCB with a red circle highlighting the Barry Cap Diode area. The diode is a small, rectangular component with a white label, located in the upper-middle section of the board, where the SAW filter was previously located.

XR-150	Original	After the change
After the change	'Final Amp' change due to 'TX LNA' part discontinuation.	
comparison	 The image shows the original green printed circuit board (PCB) of an XR-150 mobile phone. A red circle highlights a specific area on the board, which contains the TX LNA (Transmit Low Noise Amplifier) component. The board is populated with various electronic components, including a battery, a display, and a camera lens. The text 'Made in Korea' and 'XL10A-R2(AT)' is visible on the board.	 The image shows the modified green PCB of the XR-150 mobile phone after the 'Final Amp' change. A red circle highlights the same area as in the original image, but the TX LNA component has been replaced. The board is populated with various electronic components, including a battery, a display, and a camera lens. The text 'Made in Korea' and 'XL10A-R2(AT)' is visible on the board.

XR-150	Original	After the change
After the change	IC is one-chiped in function. Removal of parts due to deletion of unused functions.	
comparison	 The image shows the original printed circuit board (PCB) for the XR-150. It is a green PCB populated with various electronic components. A red circle highlights a specific area at the bottom of the board, which contains several integrated circuits (ICs) and other components, indicating a multi-chip configuration.	 The image shows the modified PCB after the change. The board has been simplified, with several components removed. A red circle highlights the same area as in the original image, but now it contains only a single, larger integrated circuit (IC), demonstrating a one-chip configuration.